

SEMICONDUCTOR LASER DEVICE

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Abstract

PROBLEM TO BE SOLVED: To obtain a semiconductor laser device using a laser chip, which does not cause mis-alignments during a die bonding process and can be prevented from being short-circuited and on one surface of which positive and negative electrodes are formed.

SOLUTION: In a semiconductor laser device which is constituted by mounting a semiconductor laser chip 200, having a plurality of electrodes 203 and 204 on one surface on a mounting member 101 having conductive film patterns 102 and 103 facing opposite the electrodes 203 and 204 on its mounting surface, the electrodes 203 and 204 are respectively connected to their corresponding conductive film patterns 102 and 103 by soldering 104 and 105, and the laser chip 200 is fixed on the member 101 with an insulating material containing resin 106.

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